

09-10-2002

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102216764

To the Honorable Commissioner of Patents and Trademarks

is or copy thereof.

1. Name of conveying party(ies):

Koji Ihara
Atsushi Kuribayashi
Tatsuya Yamamoto

Hitomi Sahara
Takeshi Tsukada
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9-3-02

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

Name and address of receiving party(ies):

Name: Sony Corporation

Internal Address: _____

Street Address: 7-35 Kitashinagawa 6-chome
Shinagawa-ku, Tokyo, Japan

City _____ State _____ ZIP _____

Additional name(s) & address(es) attached? ☒ Yes ☐ No

3. Nature of Conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other _____

Execution Date: July 31, 2002, August 2, 2002, August 5, 2002
August 8, 2002

4. Application number(s) or patent number(s):

10,233,648

If this document is being filed together with a new application, the execution date of the application is July 31, 2002, August 2, 2002, August 5, 2002
August 8, 2002

A. Patent Application No.(s)

B. Patent No.(s)

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Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Jay H. Maioli
Internal Address: Cooper & Dunham LLP

Street Address: 1185 Avenue of the Americas

City: New York State: New York ZIP: 10036

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 40.00

☒ Enclosed

☐ Authorized to be charged to deposit account

8. Deposit account number:

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9. Statement and signature.

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Jay H. Maioli, Reg. No. 27,213
Name of Person Signing

Jay H. Maioli
Signature

September 3, 2002
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PATENT
REEL: 013260 FRAME: 0530

Additional Names and Adresses of Receiving Parties:

Denso Corporation

1-1, Showa-cho, Kariya-city,
Aichi 448-8661, Japan

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

Navigation Device, Digital Map Display System, Digital Map Displaying Method
in Navigation Device, and Program

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, (1) Sony Corporation and (2) Denso Corporation, a Japanese corporation with offices at (1) 7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo 141-0001 Japan and (2) 1-1, Showa-cho, Kariya-city, Aichi 448-8661 Japan (hereinafter reference as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereof;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereof;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

International Application Number _____
International Filing Date _____
U.S. Serial Number _____
U.S. Filing Date _____

This assignment executed on the dates indicated below.

Koji IHARA July 31, 2002
Name of first or sole inventor Date

Chiba, Japan
Residence of first or sole inventor

Koji Ihara
Signature of first or sole inventor Execution date of U.S. Patent Application

Atsushi KURIBAYASHI August 2, 2002
Name of second inventor Date

Kanagawa, Japan
Residence of second inventor

Atsushi Kuribayashi
Signature of second inventor Execution date of U.S. Patent Application

Tatsuya YAMAMOTO
Name of third inventor
August 2, 2002
Date

Chiba, Japan
Residence of third inventor

Tatsuya Yamamoto
Signature of third inventor
Execution date of U.S. Patent Application

Hitomi SAHARA
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Signature of fourth inventor _____ Execution date of U.S. Patent Application _____

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Residence of fifth inventor _____

Signature of fifth inventor _____ Execution date of U.S. Patent Application _____

Yoshinori WATANABE
Name of sixth inventor _____ Date August 8, 2002

Aichi, Japan
Residence of sixth inventor _____

Yoshinori Watanabe
Signature of sixth inventor _____ Execution date of U.S. Patent Application _____